

## Single N-Channel MOSFET

### ■ DESCRIPTION

SMC7002 is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss needed in small outline surface mount package.

### ■ PART NUMBER INFORMATION

**SMC 7002 E SN - TR G**

a	b	c	d	e	f
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a : Company name.

b : Product Serial number.

c : ESD Protection

d : Package code      SN: SOT-23

e : Handling code      TR: Tape&Reel

f : Green produce code G: *RoHS Compliant*

### ■ FEATURES

**$V_{DS} = 60V, I_D = 0.46A$**

$R_{DS(ON)} = 1.2\Omega$ (Typ.) @  $V_{GS} = 10V$

$R_{DS(ON)} = 1.8\Omega$ (Typ.) @  $V_{GS} = 4.5V$

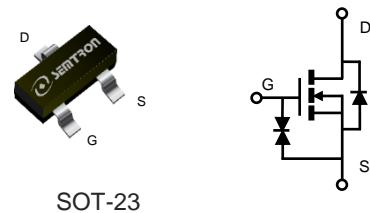
◆Fast switch

◆ESD Protection Diode Embedded

### ■ APPLICATIONS

◆Hand-Held Instruments

◆Analog Switching Application.



### ■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A=25^\circ C$	0.46
		$T_A=70^\circ C$	0.39
$I_{DM}$	Pulsed Drain Current <sup>A</sup>	1.2	A
$P_D$	Power Dissipation <sup>B</sup>	$T_A=25^\circ C$	0.7
		$T_A=70^\circ C$	0.4
$T_J$	Operation Junction Temperature	-55/150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ C$

### ■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>C</sup>	Steady-State	350	$^\circ C/W$

**ELECTRICAL CHARACTERISTICS( $T_A = 25^\circ\text{C}$  Unless otherwise noted)**

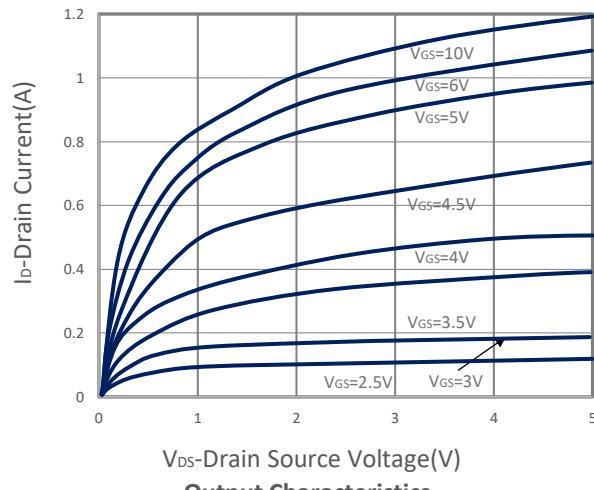
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.7	1	V
$I_{GSS}$	Gate Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$ $T_J = 25^\circ\text{C}$			1	$\mu\text{A}$
		$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$ $T_J = 125^\circ\text{C}$			10	
$R_{DS(\text{ON})}$	Drain-source On-Resistance <sup>D</sup>	$V_{GS} = 10\text{V}, I_D = 0.46\text{A}$ $V_{GS} = 4.5\text{V}, I_D = 0.3\text{A}$		1.2 1.8	1.6 3	$\Omega$
$G_f$	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 0.1\text{A}$		0.25		S
<b>Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage <sup>B</sup>	$I_S = 1\text{A}, V_{GS} = 0\text{V}$		0.7	1	V
$I_S$	Continuous Source Current				0.2	A
<b>Dynamic and Switching Parameters</b>						
$Q_g$	Total Gate Charge	$V_{DS} = 30\text{V}, V_{GS} = 10\text{V}$ $I_D = 0.2\text{A}$		1.2	1.7	nC
$Q_{gs}$	Gate-Source Charge			0.1	0.14	
$Q_{gd}$	Gate-Drain Charge			0.23	0.3	
$C_{iss}$	Input Capacitance	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$		31	43	pF
$C_{oss}$	Output Capacitance			5.3	7	
$C_{rss}$	Reverse Transfer Capacitance			3.8	5	
$t_{d(on)}$	Turn-On Time <sup>E</sup>	$V_{DD} = 30\text{V}, V_{GEN} = 10\text{V},$ $R_G = 3\Omega, I_D = 0.2\text{A}$		3	4.8	nS
$t_r$				6	9.8	
$t_{d(off)}$	Turn-Off Time <sup>E</sup>			12	19.2	
$t_f$				9	14.4	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

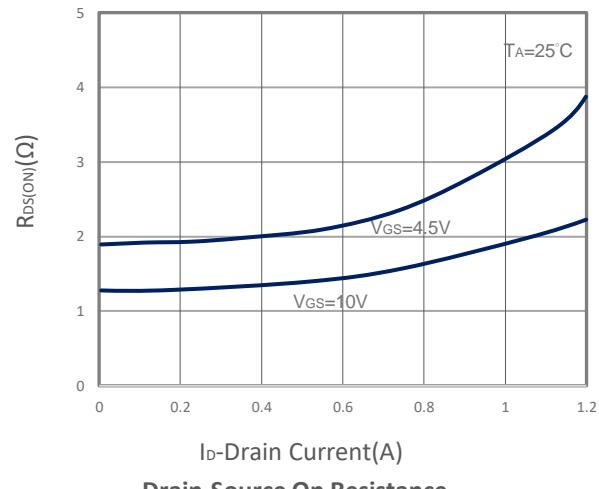
- A. The value of  $R_{\theta JA}$  is measured with the device in a still air environment with maximum junction temperature  $T_J(\text{MAX}) = 150^\circ\text{C}$  (initial temperature  $T_A = 25^\circ\text{C}$ ).
- B. The  $T_J(\text{MAX}) = 150^\circ\text{C}$ , using junction-to-ambient thermal resistance.
- C. Surface-mounted on FR-4 board using 1 sq-in pad, 2 oz Cu, in a still air environment with  $T_A = 25^\circ\text{C}$ .
- D. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- E. Pulsed width limited by maximum junction temperature.

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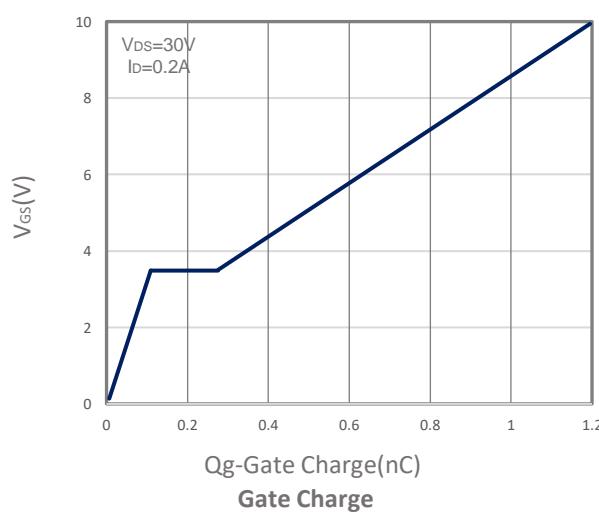
## TYPICAL CHARACTERISTICS



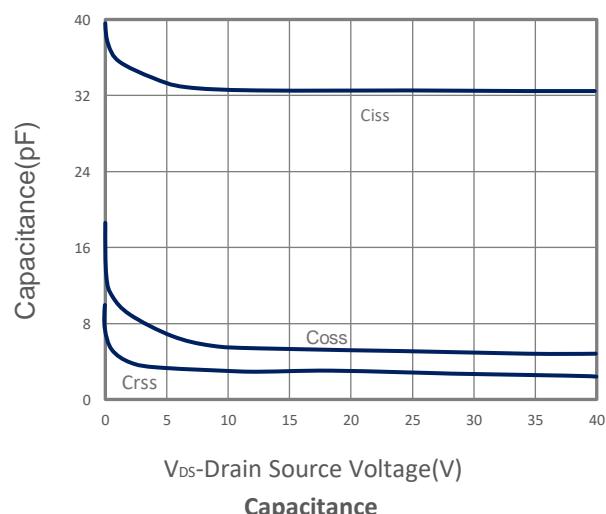
Output Characteristics



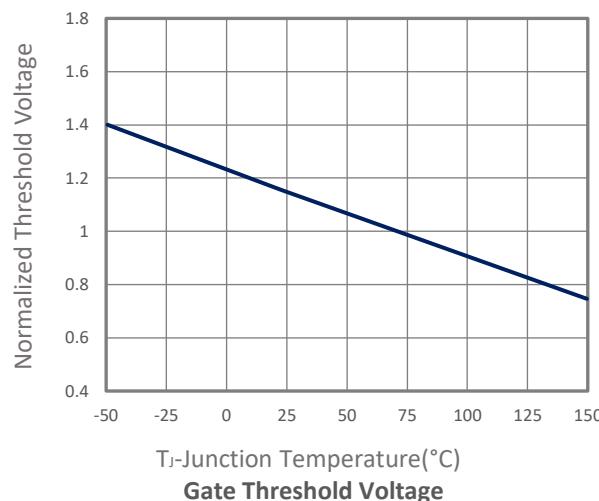
Drain-Source On Resistance



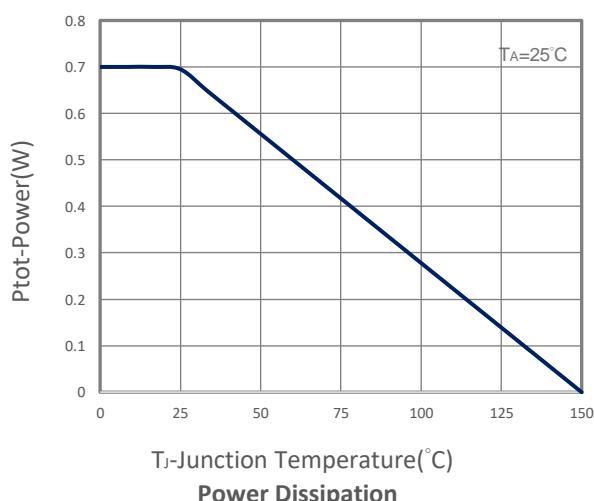
Gate Charge



Capacitance

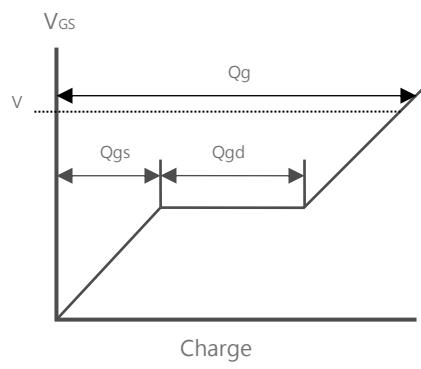
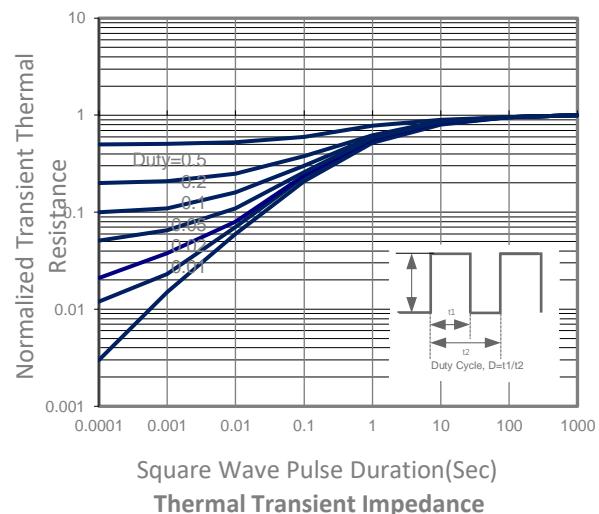
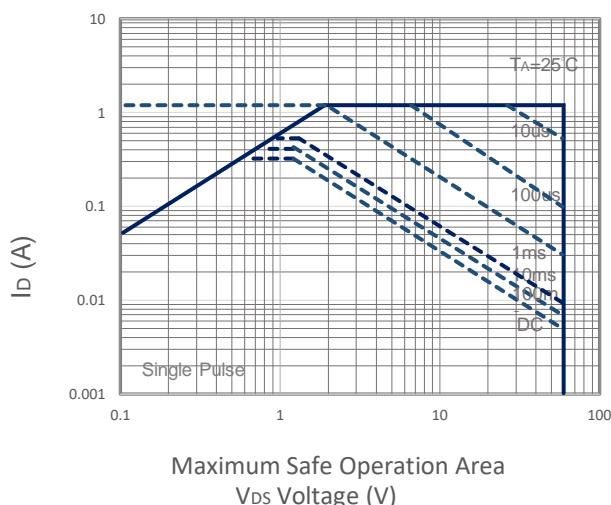
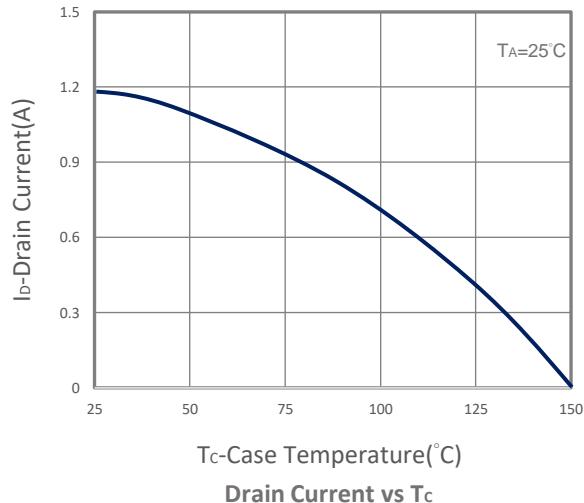
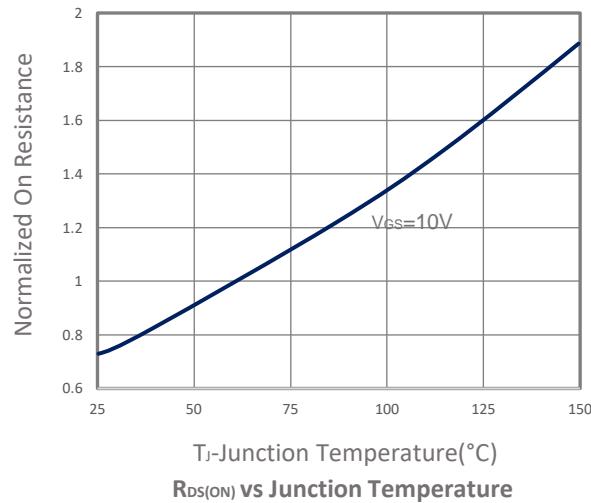


Gate Threshold Voltage

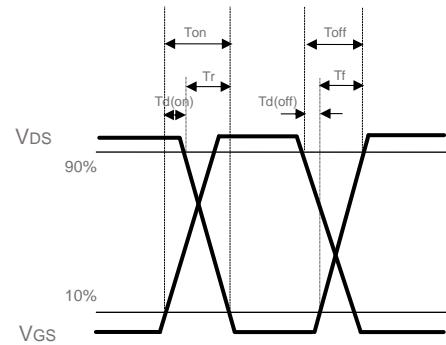


Power Dissipation

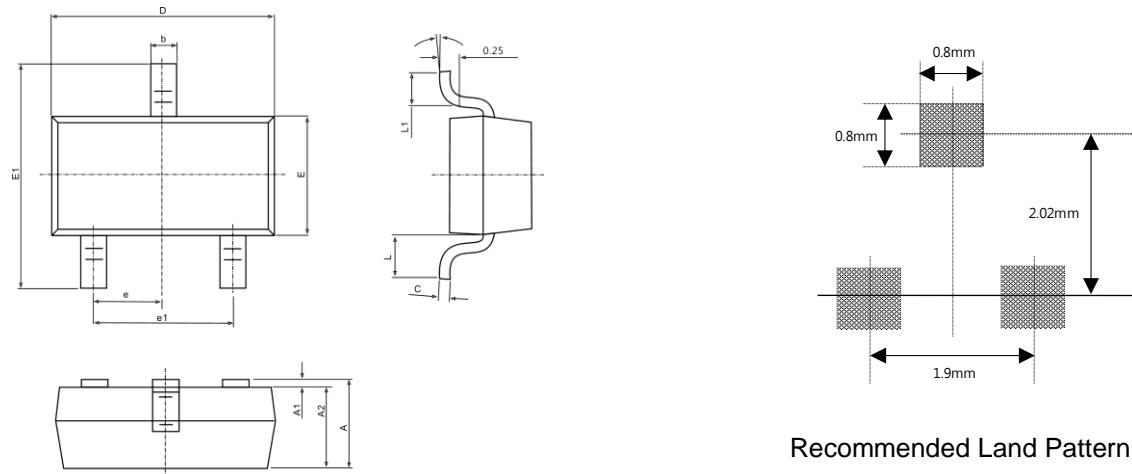
## TYPICAL CHARACTERISTICS



Gate Charge Waveform



Switching Time Waveform

**SOT-23 PACKAGE DIMENSIONS**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
$\theta$	0°	8°	0°	8°